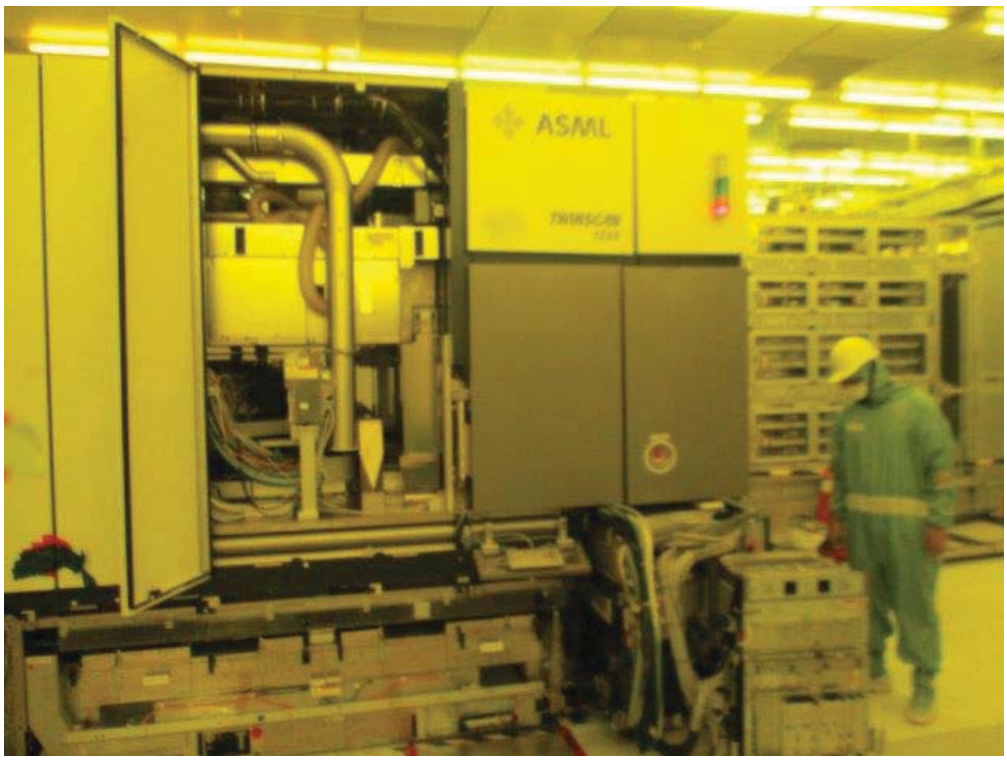
ASML Twinscan XT 1250 D ArF Scanner, 12"

Asset ID: 36999



Configuration and Photos on Following Pages

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QUICK LEAD TIMES | QUALITY EQUIPMENT | COMPETITIVE PRICING

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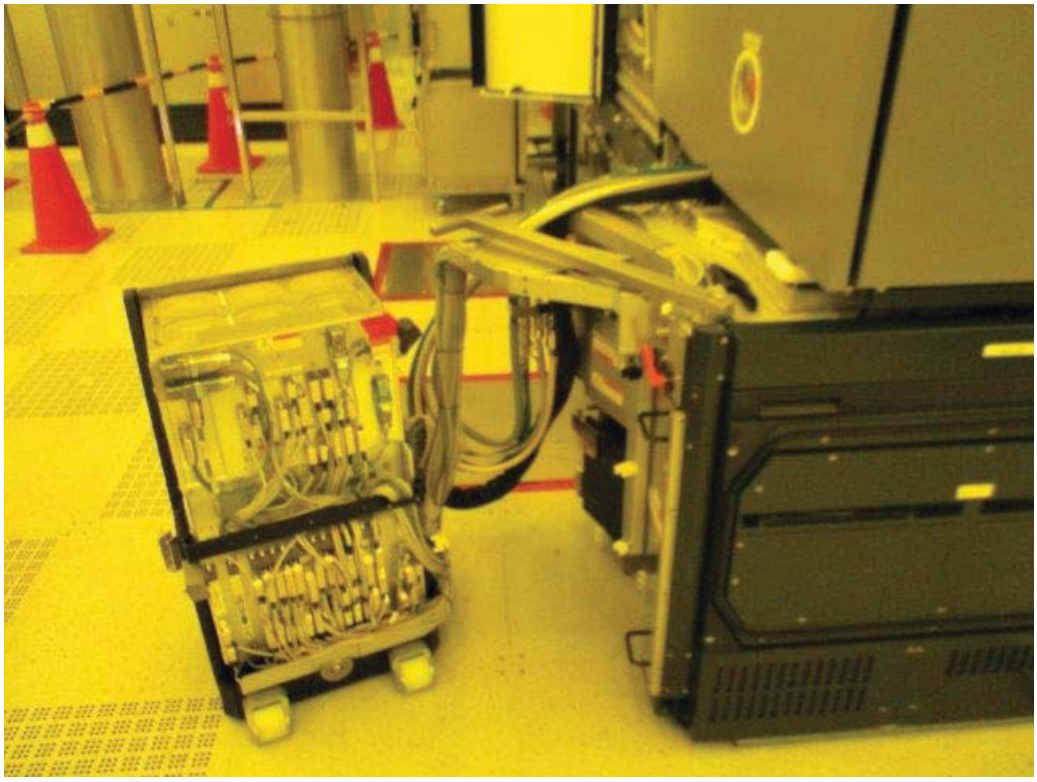

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QUICK LEAD TIMES | QUALITY EQUIPMENT | COMPETITIVE PRICING

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Configuration:

- 193nm
- Track Pre-warning signal (APR)s: APR enabled
- Avoid Track INPUT/OUTPUT conflicts, Raise AS after APRs: Avoid Track
- INPUT/OUTPUT conflicts enabled
- Active wafer release for dry WSs: FALSE
- Closing disk types: No closing disk present
- Safeguard to prevent loading of reticles with too wide or mispositioned pellicles: Disabled Continuous clampable wafer table for dry WSs: Absent
- Type of wafer table on chuck 1 & 2 for immersion machines: Zerodur version 1
- WS Immersion throughput packages: None
- WS Immersion thermal control packages: None
- Wafer Stage Configurations: Wafer Stage type 2 configuration
- Wafer Carrier Locations: Right
- Wafers per Carriers: 25
- Wafer Mark Sensors: Absent
- Wafer Id Readers: Absent
- Wafer Tracks: Present
- Wafer Stage Types: Dual Chuck
- Wafer Stress Relaxations: FALSE
- Lower Docking Plates: Present
- WS Balance Masss: Stainless Steel
- WH Robot Power Amplifiers: CPM 20
- Wafer Stage Fast Stiff X Move Electronics: Present
- Wafer Stage Mirror Block Down Electronics: Present
- Universal Prealignments: Disabled
- Interferometer axis version at exposures: 3 plus 1 axis
- Wafer Handling Pneumaticss: Dedicated
- Wafer Switchs: Absent

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Configuration (continued) -

- Chuck 1 & 2 wafer sizes: 300mm
- Type of immersion hood for immersions: None
- Specifies chuck1 & 2 layout relev. for Immersions: Chuck does not support immersion
- Specifies chuck1 & 2 configs: Dry
- Specifies chuck1 & 2 versions: not specified
- Changed Short Stroke diff XY controllers: Disabled
- Docking wheels at WH unloads: Present
- Docking plate heights: Low
- Immersion Hood versions: Absent
- Carrier Handler Types: Mark I 300 Foup
- Wafer Handling Load & Unload Robot Types: Double Fold Arm, 12 mm Z stroke
- Wafer Handling Store Units: Absent
- Wafer Handler wrt BF Shifted in Zs: Not Shifted
- Reticle streaming lites: Disabled
- Enhancements in Reticle Monitors: no enhancements
- Reticle streaming: Disabled
- Improvements for reticle handlings: Disabled
- Extend IRIS maximum particles scanned to 50000.s: Absent
- Zeroing type for Encoders Measurement Systems: Using extra hall sensors for zeroing
- Reticle Stage Chuck Types: Glued Leafspring, TYPE_2: Glued LS, Pneum. GC, IFM / ENC Nitrogen purging of Reticle Stages: RS is not purged
- Reticle Carrier Locations: Right
- Integrated Reticle Inspection Systems: PPD1 with IRIS1 functionality
- Integrated Reticle Librarys: IRL with original functionality

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Configuration (continued) -

- Reticle Sizes: 6 inch
- Reticle Carrier Tag Readers: Present
- Reticle Stage Long Stroke Motor Types: Cobalt Ferro 18 teeth
- Reticle Stage Long Stroke Configs: TYPE_3:CoFe_18 motor, SB controlled, int. vacuum supply, pneum GC
- Automated Reticle Transport Systems: Absent
- Reticle Stage Lenscooler Boxes: Lenscooler Box with anti-aliasing Filter
- Maximum Reticle ID Lengths: 24 Characters
- Reticle Stage Measurement System on Scans: Heidenhain Encoders
- Relative direction of ws to rs on the X axis: Same
- RS Object Fields: Normal
- Reticle exchange types: Retex option: E
- Iris feature Scans: Absent (Overrules Absent)
- Reticle Handler types: Original
- 2D Barcode Readers: Absent
- Integrated Reticle Inspection System Configurations: Disable creation of OSIRIS viewable files.
- WS Immersion Hood Only Testrigs: Absent
- Version of RS/WS IO librarys: Version 1
- Dynamic Performance Calculations: Mark 1
- Stages Sample Rates: 5.0 kHz
- Interferometer Electronics: Ifsr
- Capacitive z-height sensor type.s: Dual Z sensor board
- Ifm config at measure sides: 8 axes
- Dose System Performance Test sequences: Test sequence 1
- PEP-ADC Intensitys: Disable PEP-ADC Intensity
- Online Lamp Peak: Disable Online Lamp Peak

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Configuration (continued) -

- Dose Intensity Optimizations: Dose Intensity Optimization
- Carrier Handler Types: Mark I 300 Foup
- Wafer Handling Load & Unload Robot Types: Double Fold Arm, 12 mm Z stroke
- Wafer Handling Store Units: Absent
- Wafer Handler wrt BF Shifted in Zs: Not Shifted
- Reticle streaming lites: Disabled
- Enhancements in Reticle Monitors: no enhancements
- Reticle streaming: Disabled
- Improvements for reticle handlings: Disabled
- Extend IRIS maximum particles scanned to 50000.s: Absent
- Zeroing type for Encoders Measurement Systems: Using extra hall sensors for zeroing
- Reticle Stage Chuck Types: Glued Leafspring, TYPE_2: Glued LS, Pneum. GC, - IFM / ENC Nitrogen purging of Reticle Stages: RS is not purged
- Reticle Carrier Locations: Right
- Integrated Reticle Inspection Systems: PPD1 with IRIS1 functionality
- Integrated Reticle Librarys: IRL with original functionality
- Reticle Sizes: 6 inch
- Reticle Carrier Tag Readers: Present
- Reticle Stage Long Stroke Motor Types: Cobalt Ferro 18 teeth
- Reticle Stage Long Stroke Configs: TYPE_3:CoFe_18 motor, SB controlled, int. vacuum supply, pneum GC
- Automated Reticle Transport Systems: Absent
- Reticle Stage Lenscooler Boxes: Lenscooler Box with anti-aliasing Filter
- Maximum Reticle ID Lengths: 24 Characters
- Reticle Stage Measurement System on Scans: Heidenhain Encoders
- Relative direction of ws to rs on the X axiss: Same
- RS Object Fields: Normal

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Configuration (continued) -

- Reticle exchange types: Retex option: E
- Iris feature Scans: Absent (Overrules Absent)
- Reticle Handler types: Original
- 2D Barcode Readers: Absent
- Integrated Reticle Inspection System Configurations: Disable creation of OSIRIS viewable files.
- WS Immersion Hood Only Testrigs: Absent
- Version of RS/WS IO librarys: Version 1
- Dynamic Performance Calculations: Mark 1
- Stages Sample Rates: 5.0 kHz
- Interferometer Electronics: Ifsr
- Capacitive z-height sensor type.s: Dual Z sensor board
- Ifm config at measure sides: 8 axes
- Dose System Performance Test sequences: Test sequence 1
- PEP-ADC Intensitys: Disable PEP-ADC Intensity
- Online Lamp Peak: Disable Online Lamp Peak
- Dose Intensity Optimizations: Dose
- Intensity Optimization
- Test Table Z Axiss: Worm Wheel
- PUPICOMs/ Architectures: Present/ DC Motor with gearbox Number of Z Lens Manipulatorss: 5
- Number of Active Lens Elementss: 1
- Number of Bi-directional Active Lens Elementss: 0
- Number of Active Manipulator Elementss: 0
- Number of Active Elementss: 1
- Number of Half Dome Mirrorss: 0
- Number of Semi-Active X-Y Lens Manipulatorss: 4

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Configuration (continued) -

- Setup sensor board versions: Setup SSD version 1
- Imaging Generic Power Amplifiers: Generic Power Amplifier Imaging Control Rack Configurations: IPDR
- Type of projection multiplexer boards: MUX Absent
- LEC Rack in Electronic Architectures: Present
- Projection GPA Configuration Versions: Version 2
- Number of Lens NEXZ Manipulatorss: 5
- Number of Lens Z Manipulators Using Camdisks: 0 Spotsensor surface coatings: Bilatal
- Energy Sensors: VLOC
- Spot Sensor Chuck 1s & 2s: VLOC
- Modelling for MAXYSs: Absent
- Uniformity Improvement Packages: Present
- Number of pre-amps available per Z-manipulators: 0 Immersions: Absent
- Pupil measurements with ILIASs: Present
- Automatic CUAs: Absent
- Beam Controls: Beam adjustment
- Extended Spot Sensor Matchings: Present - Number of Rxms/ Ryms: 5/5
- Diaphragm Limiters: Absent
- NA1 motor types: None
- Spot Sensor Reticle Stages: Absent
- Smooth Field Uniformitys: Absent
- Exchangeable Last Lens Elements: Present
- Exchangeable Pupil Lens Elements: Absent
- Number of manipulable ELLE axess: 0
- UV Shutter versions: UV Shutter version 1
- Dosecontrol Hardwares: ISB
- Illuminator platforms: Aerial 2

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Configuration (continued) -

- Polarizations: Absent
- Automatic PCE exchangers: Absent
- Automatic CUA exchanger architectures: Not applicable Test table architectures: Aerial 2
- Illumination modes: All illumination modes
- DUV Lightsource Power Levels: 45.00 Watt
- Lens Top Tool Connections: Lens Top Tool can be mounted on top of the Lens Scanning Energy Sensor Calibrations: Static Energy Sensor Calibration
- Position of Spot Sensor on Chuck 1s: Spot - Sensor Position on Chuck 1 layout 1
- Position of Spot Sensor on Chuck 2s: Spot Sensor Position on Chuck 2 layout 1
- Z-capture for low relfectivity wafers: Off
- TIS plate deformation corrections: Disabled
- FSM Flexibility packages: Disabled
- Field width optimised leveling: Disabled
- Constrained fits: Disabled
- Levelling throughput improvement on measure sides: No levelling throughput package
- Point-to-Point LS Machine Matchings: Disabled
- Circuit Dependent FECs: Present
- Focus Monitorings: Present
- Extended LS areas: Disabled
- Air Gauges: Absent
- Type of Air Gauges: No Air Gauge device present
- Reticle shape corrections: Disabled (Overrules Enabled)
- LS focus nodes: LS focus node 3
- Level Sensor Processing Racks: LCSR
- LS_PEMM_CONFIGs: Present

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Configuration (continued) -

- LS_CPU_CONFIGs: 3 CPU's available
- Base Liner overlay high order intrafields: Disabled
- BaseLiner focus high order intrafields: Disabled
- BaseLiner focus control.s: Disabled
- Pattern Matcher fullchips: Absent
- Pattern Matchers: Absent
- Maximum numerical aperature (NA) that can be used in Lot Productions: level 0
- Log missed translations: Disabled
- Allow even orders usages: Present
- Multilingual UIs: Absent
- Improved Maintenance action scheduling.s: Disabled
- Recipe Creators: Light
- Lot Report Data Categorys: Enhanced Diagnostics
- CDCs: Enabled
- EFESEs: Absent
- PED control modes: Absent
- Proximity Matchings: Present

mbds controls: Present

- Enhanced exposures 1s: Present
- Data collection not covered by FOCUS and - OVERLAYs: InformPro Data Collection disabled
- Overlay Data Collections: Disabled
- XML Lot Report Content Levels: Basic
- Enable the Maintenance Assistants: Disable Maintenance Assistant
- EDA Interfaces: Disabled
- Equipment Constants via SECS interfaces: Disabled

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Configuration (continued) -

- LCI WaitWatcher plug-ins: Absent
- Reorder Lot Services: Absent
- Shot Data Collections: Absent
- Focus Data Collections: Absent
- Alignment Recipe Overrides: Disabled
- Enable to support SMASH XY mark types.s: not supported
- Specifies which mark types are supporteds: ASML marks only
- Alignment laser configurations: 2 color laser
- OADB Improved Dynamic Ranges: Disabled
- Board configurations: ODB + ADB
- Alignment Camera Mirrors: Absent
- Athena Narrow Marks Twinscans: Present
- Alignment Sensor Types: Athena Narrow Marks OM
- Athena Focus Improvements 1s: Present
- Max alignment speeds: Setting 2
- AA processing racks: AACR processing rack
- Particle Extraction Mass Flow Meters: Absent

purging configurations: purging CONFIG 3

- Bubble Extraction Seal Settings: Not Applicable
- Ultra Pure Water flow controller (WICC)s: absent
- LCW Circuit set-ups: Flow Version 1
- In situ Wafer TablesStone Cleanings: Absent
- Clean Air Configurations: Others
- Metroframe Circuit Water Cabinets: Absent - CT Miscellaneous Racks: Present
- Clean Air Temperature Controls: Driver and ACC
- Purge Hoods configurations: Compressed Clean air and Extremely Clean Dry air Nitrogen

Purge Utility Controls: Absent

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Configuration (continued) -

- Reticle Cleanings: Absent
- Metroframe types: TYPE_I
- Inlet restriction for clean airs: Inlet restriction at right side
- Reticle Stage purged mini environments: Present
- Gas Control Unit Types: High Flow (HF)
- Wet Imaging Control Cabinets: Not Applicable
- Readout location of Pneumatic Facility Unit sensors: Machine Base Diagnostics System (MBDS)
- Laminar Bottom Hoods: Absent
- Extreme Clean Humiditied Airs: Absent
- Lens Circuit Water Flows: High
- Motor Circuit Water Flows: Normal
- SPM temp correction for lens axiss: Disabled
- 2 Sided IFM-beams for WS-X (expose/ measure)s: Not available
- Diff pressure correction for IFM beams: Absent
- IFM Laser Configurations: AOM Recombo Laser
- Position Control Rack Configurations: Rack Configuration type 3
- Position Control Power Rack Configurations: TYPE_3: Stages Power Rack upto E-spec Number of Motion Controllerss: 5 Motion Controllers present
- Position Control Motion Control racks: PMCR
- Reticle Stage Short Stroke X/Y11/Y12/Y21/Y22/Y11/Y11 amp.s: PADC 100V/16A
- Wafer Stage Short Stroke 1 XY1/ XY2/XY3 amp.s: PADC 100V/16A
- Wafer Stage Short Stroke 2 XY1/ XY2/XY3 amp.s: PADC 100V/16A
- Reticle Stage Short Stroke Z1/Z2/Z3 amp.s: Pass Low Current 8.5A
- Wafer Stage Short Stroke 1 Z1/Z2/Z3 amp.s: Pass Low Current 8.5A
- Wafer Stage Short Stroke 2 Z1/Z2/Z3 amp.s: Pass Low Current 8.5A

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Configuration (continued) -

- Reticle Stage Long Stroke Y11/Y12/Y21/Y22 amp.s: 450V20A: PAAC AT-pepD
- Reticle Balance Mass 1/2 amp.s: 450V20A: PAAC AT-pepD
- Wafer Stage Long Stroke E/M X amp.s: 400V16A: PAAC AT-D
- Wafer Stage Long Stroke E Y1/Y2/CS amp.s: 400V16A: PAAC AT-D
- Wafer Stage Long Stroke M Y1/Y2/CS amp.s: 400V16A: PAAC AT-D
- Wafer Stage Balance Mass 11/12/21/22 amp.s: 325V14A: PAAC AT-C
- Pressure update rate for fringelength corrections: Pressure update rate 2 or 4 Hz
- TestStreams: TestStream disabled
- Performance Enhancement Packages: None
- PEP Image Streamings: Present
- Lot Overhead Reductions: LOR2
- Extended Zone Alignments: Disabled
- Intrafield Higher Order Process Correctionss: Disabled
- SMASH Reuse Capture Information in Stage Alignments: Coarse capture scans are done on all stage alignment marks.
- Allow wafer plane deviation check with Focus Monitorings: Disabled
- Parameter indicates how long overlay data will be stored.s: Short retention period.
- Level sensor Ry drift corrections: Disabled
- Fading Control Switchs: Disabled
- Improved wafer reject modes: Disabled
- Automated Lens Heating Calibrations: Disabled
- Lens heating History in LH Feedforwards: Enabled
- Allow different Exp,TIS Align sets: Absent
- Imaging Fading Controls: Disabled
- Gridmappers: Disabled
- 2D grid corrections: Enabled

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Configuration (continued) -

- Double TIS scans: Disabled
- Symmetrical Reticle Alignments: Disabled - Ast offset correction in TIS LHFB/ LOCO (Version 3)s: Enabled
- Choice of avoidance routing.s: Absent
- NEXZ-tilt per exposures: The NEXZ-tilt cannot be adjusted per exposure.
- Off-axis slits: Projection lens has no off-axis slit.
- Improved Edge Field Levelings: Disabled
- Enhanced Throughput Reticle Alignments: Present
- Wavelength Adjustables: Adjustable
- Allow L1L7 Type 1 Optimizations: Absent
- Lot Alignment Report Encryptions: Unencrypted
- Stage Alignment Filters: Present
- Lot Correction Sequences: Unencrypted
- Stage Alignment Filters: Present
- Lot Correction Sequences: Type B
- Lens Heating Feedbacks: Present
- Application Specific Lens Heating Calibration and Verifications: Present Improved
- Contrast Controls: Absent
- ILIAS lens setups: Absent
- Air Gauge Improved Levellings: Absent
- Process Dependent Gain Corrections: Absent
- Enhanced Exposure Overlays: Absent
- ALE 1 Uses: Lens heating only
- Overlay Nodes: Level 0
- E-chuck Flatness Qualification Tests: Disabled
- TOP HDs: Absent

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Configuration (continued) -

- Reticle Align High Precisions: Absent
- LS spot coverages: Absent
- Layout Version Number TIS Plate 1 on Chuck 1s/2s: TIS Plate 1 Layout Version 2
- Layout Version Number TIS Plate 2 on Chuck 1s2s: TIS Plate 2 Layout Version 4
- Usage of wavelength/ Energy Sensor data by TISs: Disabled
- Indication what kind of AM controller hardware is presents: SUCR
- Piezo Active Lens Mountss: Absent
- ILIAS Functionality For Lithoguides: Present
- ISIS Functionality For Lithoguides: Absent
- SAMOS Stray Light Test For Lithoguides: Present
- PUPIL Measurement For Lithoguides: Present
- FOCAL Measurement for Lithoguides: Present
- Leveling Verification Test for Lithoguides: Present
- Lithoguide Imaging Recipess: Absent
- Dose System Performance Test for Lithoguides: Present
- ILIAS Sensor Locations: Chuck 2
- ILIAS sensor type chuck 2s: Multiple scan grid
- ILIAS sensor type chuck 1s: None
- Reticle Level Polarization Sensors: Absent - SASO robustness and fiber connectivitys: Disable SASO robustness
- Extended X width masking ranges: Disabled
- PDO offset for EFL LS spots: Disabled
- Assure System Snapshotss: not allowed
- Insert a delay time before starting a Lot (lens heating).s: Enabled
- Save throughput data to the disks: Disabled - Patch strategys: Patchlevel
- Chuck Dedications: Basic

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Configuration (continued) -

- Application Types: Scanner Application
- Number of RMCS clients: No clients
- MDL Viewers: Site View
- ZERO Fiducials: ILIAS MK2
- Machine Architectures: XT Machine Architecture
- XT Architecture Revisions: Rev1
- Machine Types: 1250
- Machine Specifications: pep-D Specification - Stand-alone Workstations: FALSE
- CP 1As/1Bs/2s/3s/4s/5s/6s: Absent
- Wafer Handler Productivitys: Level 0

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